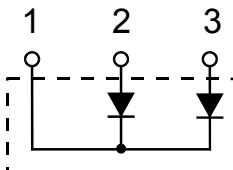
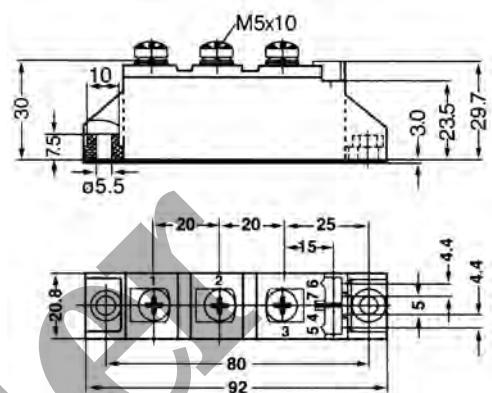


SDKF2x75-12B

Soft Recovery Behaviour Ultra Fast Recovery Epitaxial Diode Modules



Dimensions in mm (1mm=0.0394")



Product



ul.com/rsccs

	V _{RSM} V	V _{RRM} V
SDKF2x75-12B	1200	1200

Symbol	Test Conditions	Maximum Ratings	Unit
I _{FRMS}	T _C =75°C	107	
I _{FAVM}	T _C =75°C; rectangular, d=0.5	2 x 75	A
I _{FRM}	t _p <10us; rep. rating, pulse width limited by T _{VJ}	TBD	
I _{FSM}	T _{VJ} =45°C t=10ms (50Hz), sine t=8.3ms (60Hz), sine	1200 1300	A
	T _{VJ} =150°C t=10ms(50Hz), sine t=8.3ms(60Hz), sine	1080 1170	
I ² t	T _{VJ} =45°C t=10ms (50Hz), sine t=8.3ms (60Hz), sine	7200 7100	A ² s
	T _{VJ} =150°C t=10ms(50Hz), sine t=8.3ms(60Hz), sine	5800 5700	
T _{VJ} T _{stg} T _{Hmax}		-40...+150 -40...+125 110	°C
P _{tot}	T _{case} =25°C	280	W
V _{ISOL}	50/60Hz, RMS I _{ISOL} ≤1mA	t=1min t=1s 3000 3600	V~
M _d	Mounting torque (M5) Terminal connection torque (M5)	2.50-4/22-35 2.50-4/22-35	Nm/lb.in.
d _s d _a a	Creeping distance on surface Strike distance through air Maximum allowable acceleration	12.7 9.6 50	mm mm m/s ²
Weight		108	g

Sirectifier®

SDKF2x75-12B

Soft Recovery Behaviour Ultra Fast Recovery Epitaxial Diode Modules

Symbol	Test Conditions	Characteristic Values typ.	Characteristic Values max.	Unit
I_R	$T_{VJ}=25^\circ C; V_R=V_{RRM}$ $T_{VJ}=25^\circ C; V_R=0.8 \cdot V_{RRM}$ $T_{VJ}=125^\circ C; V_R=0.8 \cdot V_{RRM}$		2 0.5 34	mA
V_F	$I_F=100A; T_{VJ}=125^\circ C$ $T_{VJ}=25^\circ C$ $I_F=300A; T_{VJ}=125^\circ C$ $T_{VJ}=25^\circ C$		1.85 2.17 2.58 2.64	V
V_{TO}	For power-loss calculations only		1.48	V
r_T			3.65	$m\Omega$
R_{thJH} R_{thJC}	DC current DC current		0.550 0.450	K/W
t_{rr} I_{RM}	$I_F=150A; T_{VJ}=100^\circ C$ $V_R=600V; T_{VJ}=25^\circ C$ $-di/dt=200A/us; T_{VJ}=100^\circ C$	250	300 22 33	ns A A

FEATURES

- * International standard package
- * Copperbase plate
- * Glass passivated chips
- * Short recovery time
- * Low switching losses
- * Soft recovery behaviour
- * UL File NO.E310749
- * RoHS compliance

APPLICATIONS

- * Antiparallel diode for high frequency switching devices
- * Free wheeling diode in converters and motor control circuits
- * Inductive heating and melting
- * Uninterruptible power supplies (UPS)
- * Ultrasonic cleaners and welders

ADVANTAGES

- * High reliability circuit operation
- * Low voltage peaks for reduced protection circuits
- * Low noise switching
- * Low losses

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SDKF2x75-12B

Soft Recovery Behaviour Ultra Fast Recovery Epitaxial Diode Modules

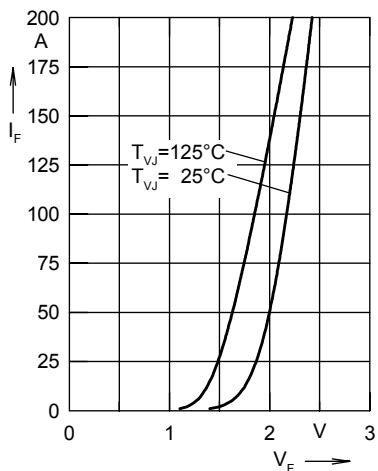


Fig. 1 Forward current I_F versus voltage drop V_F per leg

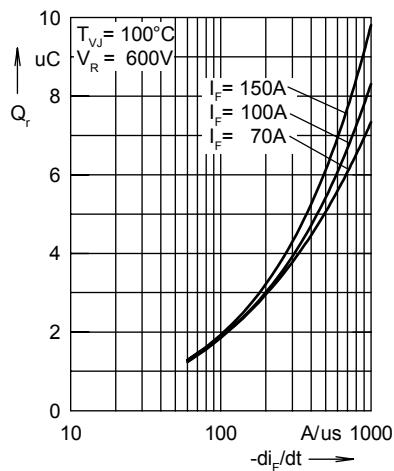


Fig. 2 Reverse recovery charge Q_r versus $-di_F/dt$

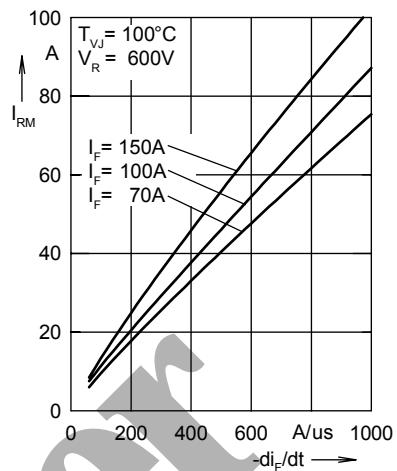


Fig. 3 Peak reverse current I_{RM} versus $-di_F/dt$

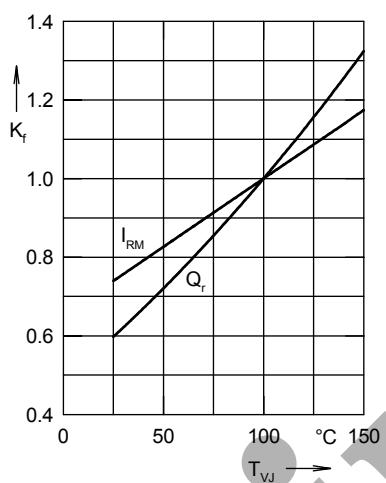


Fig. 4 Dynamic parameters Q_r , I_{RM} versus junction temperature T_{VJ}

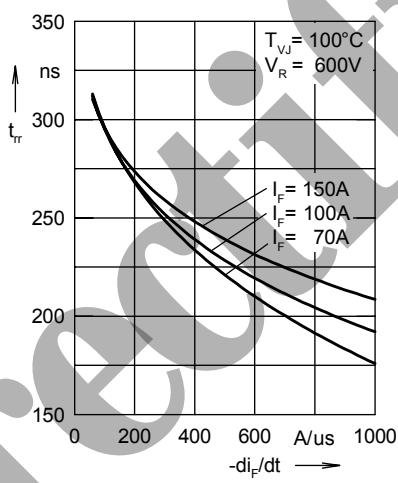


Fig. 5 Recovery time t_{rr} versus $-di_F/dt$

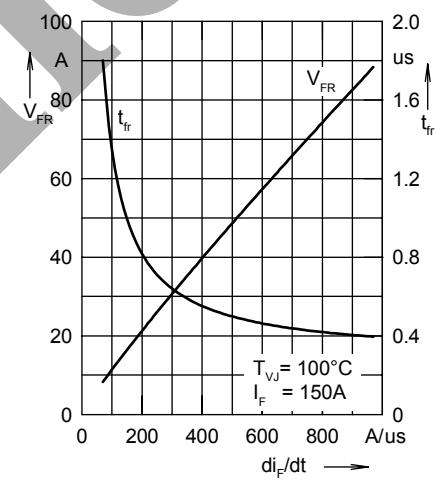


Fig. 6 Peak forward voltage V_{FR} and t_{rr} versus di_F/dt

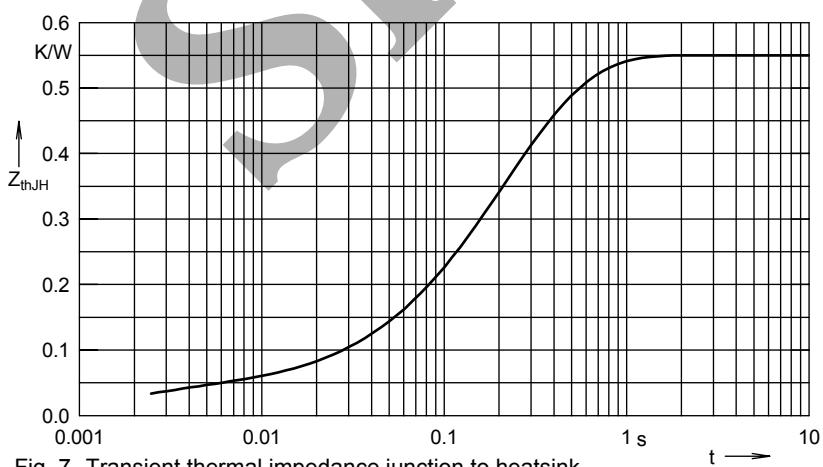


Fig. 7 Transient thermal impedance junction to heatsink

Constants for Z_{thJH} calculation:

i	R_{thi} (K/W)	t_i (s)
1	0.037	0.002
2	0.138	0.134
3	0.093	0.25
4	0.282	0.274